

TSMC99-646B



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TECHNOLOGY CENTER 2800

To: Commissioner of Patents and Trademarks  
Washington, D.C. 20231

Fr: Stephen B. Ackerman, Reg. No. 37,761  
20 McIntosh Drive  
Poughkeepsie, N.Y. 12603

Subject:

Serial No. 09/846,536

05/02/01

W. T. Chu et al

"SELF ALIGNED, LOW CONTACT RESISTANCE,  
VIA FABRICATION PROCESS"

GRP. Art. Unit 2811

O. Nadav

### RESPONSE PATENT OFFICE ACTION

Dear Sir;

In response to the FINAL Office Action dated April 26, 2002, please amend the identified application for patent as follows:

The commissioner is hereby authorized to charge payment of any additional fees involved with added Claims and the like to Deposit Account No. 19-0033

### CERTIFICATE OF MAILING

I hereby certify that this correspondence is being deposited with the United States Postal Service as first class mail in an envelope addressed to: Commissioner of Patents and Trademarks, Washington, D.C. 20231, on May 30, 2002,

Stephen B. Ackerman, Reg. No. 37,761

Signature

Date

5/30/02